



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-03-25
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Flavio Di Francesco	<b>Representative Title</b>	AMS Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BZMQ*B6AA94Q	A	BO2A	2015-03-25
Amount	UoM	Unit type	ST ECOPACK Grade	
154	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3.9-9.9-1.25	16	gull wing	
Comment	Package: Q7 SO 16 .15 TO JEDEC MS-012; MD valid for M41T94MQ6F			

QueryList : ROHS directive 2011/65/EU _ July 2011				
Query				Response
1 - Product(s) meets EU RoHS requirement without any exemptions				true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)				false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)				false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions				false
5 - Product(s) is obsolete, no information is available				false
6 - Product(s) is unknown, no information is available				false
Exemption Id.	Description			
QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BZMQ*B6AA94Q					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	8.485	mg	supplier	die	Silicon (Si)	7440-21-3		8.377	mg	987272	54538
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	2593	143
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1061	59
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	354	20
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.016	mg	1886	104
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.058	mg	6836	378
Leadframe	Copper & its alloys	31.925	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.111	mg	974503	202546
				supplier	alloy	Iron (Fe)	7439-89-6		0.732	mg	22929	4766
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.044	mg	1378	286
				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1190	247
Die attach	Other inorganic materials	1.919	mg	supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		1.439	mg	749870	9368
				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.472	mg	245961	3073
				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.008	mg	4169	52
Bonding wire	Precious metals	1.223	mg	supplier	wire	Gold (Au)	7440-57-5		1.223	mg	1000000	7962
encapsulation	Other inorganic materials	110.048	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		11.005	mg	100002	71647
				supplier	mold compound	phenol resin	9003-35-4		5.502	mg	49996	35820
				supplier	mold compound	Carbon Black	1333-86-4		1.100	mg	9996	7161
				supplier	mold compound	Silica, vitreous	60676-86-0		88.039	mg	800005	573171
				supplier	mold compound	Antimony Trioxide	1309-64-4		2.201	mg	20000	14329
				supplier	mold compound	Brominated epoxy resin	40039-93-8		2.201	mg	20000	14329